

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
16 October 2003 (16.10.2003)

PCT

(10) International Publication Number
WO 2003/085725 A3

(51) International Patent Classification⁷: **G06F 1/00**,
H01L 25/065, 23/498

(21) International Application Number:
PCT/US2003/009017

(22) International Filing Date: 26 March 2003 (26.03.2003)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
10/113,502 1 April 2002 (01.04.2002) US

CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (*regional*): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

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(81) Designated States (*national*): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU,

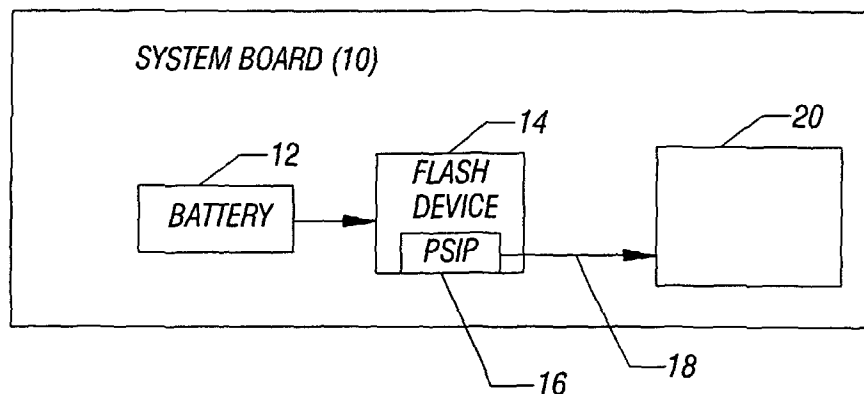
Published:

- with international search report
- before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments

(88) Date of publication of the international search report:
10 September 2004

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: IN PACKAGE POWER SUPPLIES FOR INTEGRATED CIRCUITS



(57) Abstract: A device (14) in an integrated circuit with an on chip power supply (16) may be utilized to supply power to other components (20). As a result, the overall system (10) size may be reduced and economies may be achieved.

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